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<th>ALL ANTIPO LEAD ID</th>
<th>BOARD 4</th>
<th>TID=120891</th>
<th>REV C2</th>
<th>SAM REV Not In Version Control</th>
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<td>LAYER NAME = Bottom solder</td>
<td>TID 4s</td>
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<td>PLOT NAME = Bottom solder foot</td>
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<td>11:59:52 PM</td>
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